



NOTE:
 1.MATERIAL:
 1.1 Insulator:LCP+30%Glass
 Fiber(UL94V-0) Black
 1.2 Shell: Brass/Spcc
 1.3 Contact:Brass
 1.3 Contact Plating:Gold Flash, GOLD
 PLATING ON CONTACT POINT,
 100u"MIN.TIN PLATING ON SOLDER TAILS,
 50u"MIN.NICKEL UNDERPLATING OVERALL.
 1.4 Shell:80u"Nickel plated over all
 2.SPECIFICATION:
 2.1 Current Rate:0.5Amp
 2.2 insulator Resistance:100MΩ Min
 2.3 Dielectric Strength: 500V AC Per minut
 2.4 Contact Resistance: 20mΩ Max
 2.5 Temperature:-55°C~+105°C
 "*" 標示是重點管控尺寸

PART NO.	殼材質	PLATING
70107-T-0A1 (真空盤包裝)	Brass	GOLD/TIN PLATED
70107-T-0B1 (卷帶包裝)	Brass	GOLD/TIN PLATED
70107-T-0C1 (新增料號)	Brass	GOLD(15U")/TIN PLATED
70107-T-0D1 (真空盤包裝)	Spcc	GOLD/TIN PLATED

尚益科技有限公司 JMSCONN TECHNOLOGY CO., LTD.					
PROJ		SCALE : F DO NOT SCALE DWG	MOLD NO	70107-T	
APP			MODEL	FILE NO	REV. X1
CHK					
DGN			UNIT	SHT 1 OF 1	SIZE A4
DRW	HSIEH	2012.05.20	MM		